

ABSTRACT

LEADED MCM PACKAGE AND METHOD THEREFOR

A method of packaging a leaded multi-chip package and a leaded multi-chip
5 package using a combination of substrate and leadframe. A plurality of integrated
circuit (IC) chips (4) are attached onto a laminate substrate (1) which has printed
conductive traces on both sides. Bonding wires (5, 9) are used to form interconnects
between bond pads on the IC chips and bond fingers on the substrate and between a
metallic leadframe attached to the substrate and bond fingers on the substrate. The
10 side of the substrate on which the IC chips are attached is encapsulated with
moulding compound (6). The metallic leadframe (7) is attached onto the surface of
the substrate that has not yet been encapsulated. The interconnects between the
substrate and the leadframe are then encapsulated with moulding compound and the
portion of the leadframe outside the encapsulated area is formed into a predetermined
15 shape such as gull-wing or J-shape.

Figure 8